ACCELERATE[®]**HD HIGH-DENSITY SLIM BODY ARRAYS** (0.635 mm) .025" PITCH

FEATURES & BENEFITS

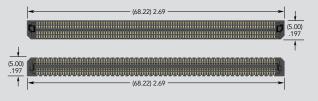
- Up to 400 positions in a 4-row design
- 5 mm, 7 mm, 9 mm, 10 mm, 11 mm, 12 mm 14 mm & 16 mm stack heights
- Slim 5 mm width body design
- Edge Rate[®] contact system optimized for signal integrity performance
- Open-pin-field for grounding and routing flexibility
- Supports 64 Gbps PAM4 (32 Gbps NRZ) applications
- PCIe[®] 6.0/CXL[®] 3.1 capable





SureWare[™] ultra rugged guide post standoffs available (GPSO)

HIGHER DENSITY THAN PREVIOUS GENERATION STRIPS



ADM6/ADF6 Series (400 total positions)

KEY SPECIFICATIONS (ADM6/ADF6)

РІТСН	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	WORKING VOLTAGE	LEAD-FREE SOLDERABLE
(0.635 mm) .025"	40 - 400	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 ℃ to +125 ℃	1.34 A per pin (4 pins powered)	155 VAC/219 VDC	Yes

PCI-SIG®, PCI Express® and the PCIe® design marks are registered trademarks and/or service marks of PCI-SIG.

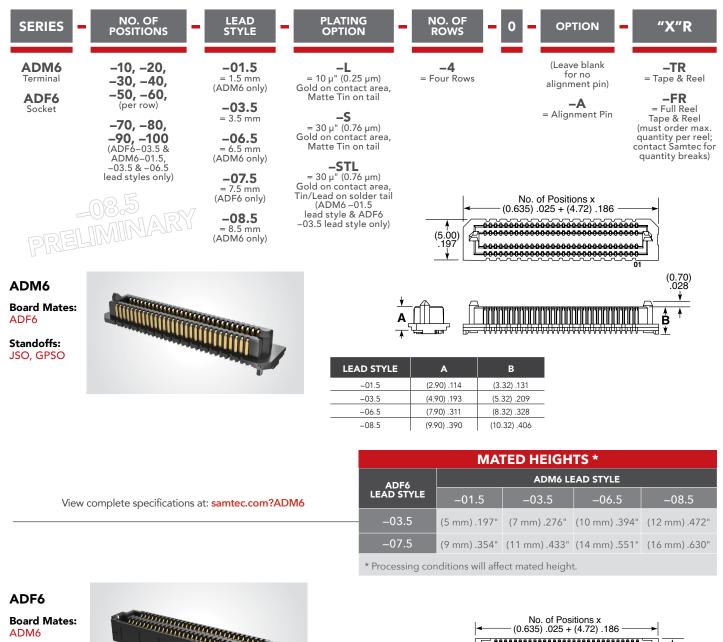
F-224 (Rev 24OCT24)

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

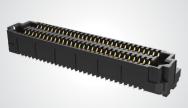




(0.635 mm) .025" PITCH • SLIM BODY OPEN-PIN-FIELD ARRAYS



Standoffs: JSO, GPSO



(0.635) .025 + (4.72) .186 $ $
\$1000000000000000000000000000000000000

LEAD STYLE	A	В
-03.5	(3.23) .127	(3.65) .144
-07.5	(7.23) .285	(7.65) .301

\$

Notes: Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?ADF6

samtec.com/AcceleRateHD